

SOT459-1

plastic low profile quad flat package; 208 leads; body 28 x 28 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP208
Package type industry code	LQFP208
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E30
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

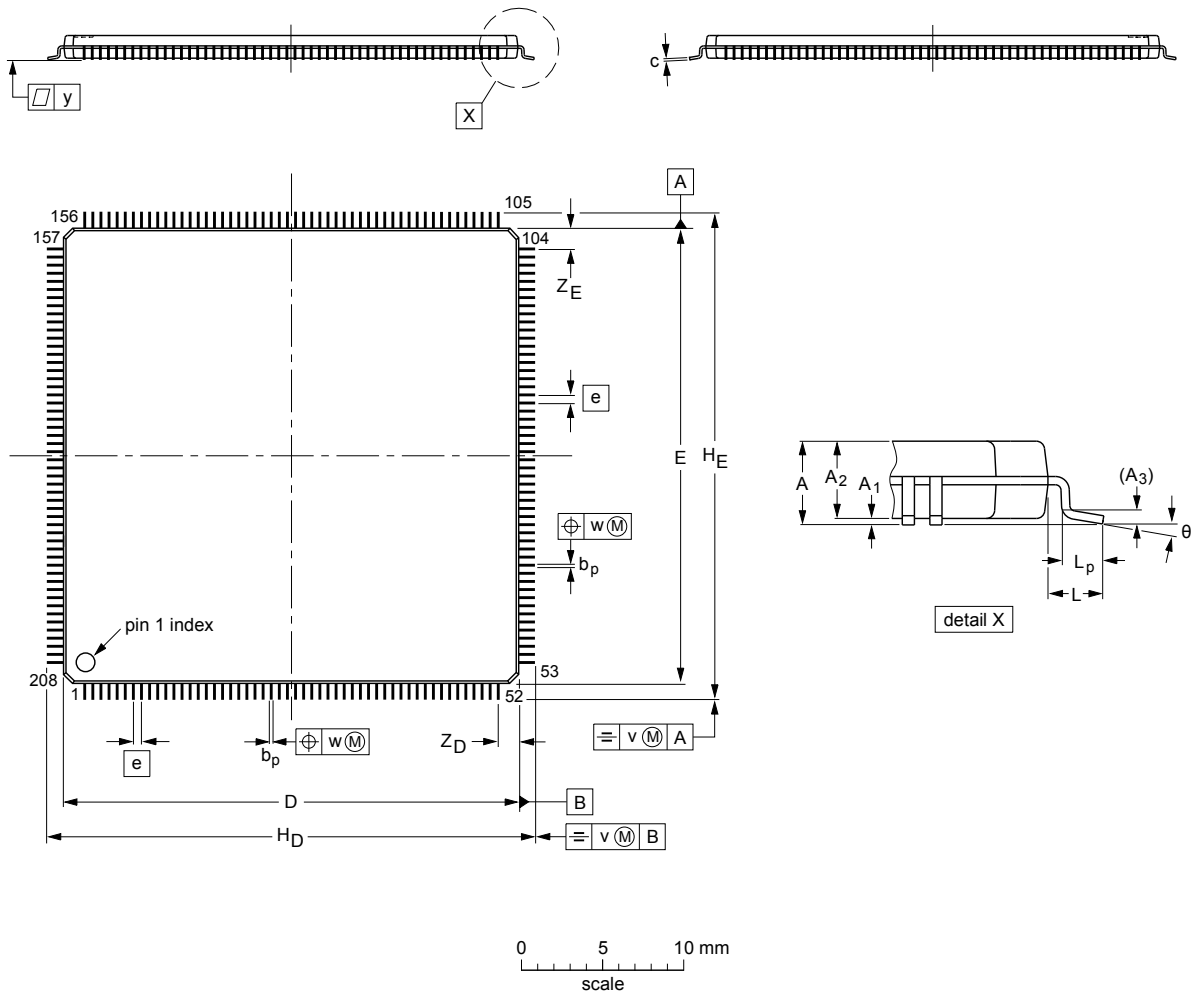
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination	-	-	208	-	



2. Package outline

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D	Z _E	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	28.1 27.9	28.1 27.9	0.5	30.15 29.85	30.15 29.85	1	0.75 0.45	0.12	0.08	0.08	1.43 1.08	1.43 1.08	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT459-1	136E30	MS-026				-00-02-06 03-02-20

Fig. 1. Package outline LQFP208 (SOT459-1)

3. Soldering

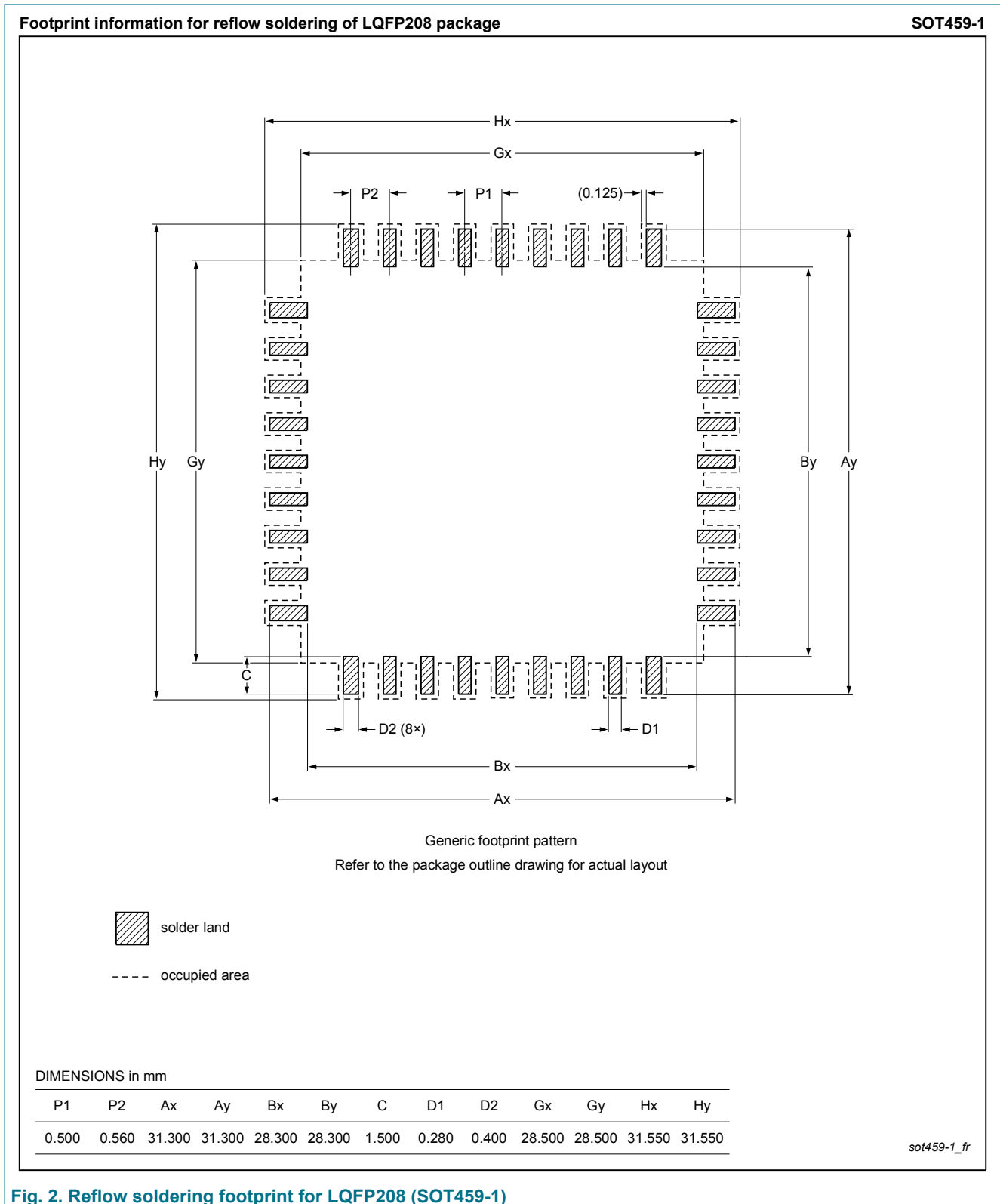


Fig. 2. Reflow soldering footprint for LQFP208 (SOT459-1)

4. Legal information

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